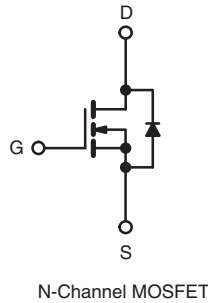
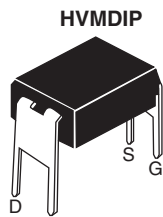


## Power MOSFET

| PRODUCT SUMMARY           |                 |     |
|---------------------------|-----------------|-----|
| $V_{DS}$ (V)              | 500             |     |
| $R_{DS(on)}$ ( $\Omega$ ) | $V_{GS} = 10$ V | 3.0 |
| $Q_g$ (Max.) (nC)         | 24              |     |
| $Q_{gs}$ (nC)             | 3.3             |     |
| $Q_{gd}$ (nC)             | 13              |     |
| Configuration             | Single          |     |



### FEATURES

- Dynamic  $dV/dt$  Rating
- Repetitive Avalanche Rated
- For Automatic Insertion
- End Stackable
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC



Available

**RoHS\***  
COMPLIANT

### DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The 4 pin DIP package is a low cost machine-insertable case style which can be stacked in multiple combinations on standard 0.1 inch pin centers. The dual drain serves as a thermal link to the mounting surface for power dissipation levels up to 1 W.

| ORDERING INFORMATION |                           |
|----------------------|---------------------------|
| Package              | HVMDIP                    |
| Lead (Pb)-free       | IRFD420PbF<br>SiHFD420-E3 |
| SnPb                 | IRFD420<br>SiHFD420       |

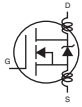

| ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C, unless otherwise noted) |                  |                |                  |      |      |
|---|------------------|----------------|------------------|------|------|
| PARAMETER   | SYMBOL           |                | LIMIT            | UNIT |      |
| Drain-Source Voltage  | $V_{DS}$         |                | 500              | V    |      |
| Gate-Source Voltage   | $V_{GS}$         |                | $\pm 20$         |      |      |
| Continuous Drain Current  | $V_{GS}$ at 10 V | $T_A = 25$ °C  | 0.37             | A    |      |
|   |                  | $T_A = 100$ °C | 0.23             |      |      |
| Pulsed Drain Current <sup>a</sup>                                 | $I_{DM}$         |                | 3.0              |      |      |
| Linear Derating Factor  |                  |                | 0.0083           | W/°C |      |
| Single Pulse Avalanche Energy <sup>b</sup>                        | $E_{AS}$         |                | 51               | mJ   |      |
| Repetitive Avalanche Current <sup>a</sup>                         | $I_{AR}$         |                | 0.37             | A    |      |
| Repetitive Avalanche Energy <sup>a</sup>                          | $E_{AR}$         |                | 0.10             | mJ   |      |
| Maximum Power Dissipation   | $T_A = 25$ °C    |                | $P_D$            | 1.0  | W    |
| Peak Diode Recovery $dV/dt^c$                                     |                  |                | $dV/dt$          | 3.5  | V/ns |
| Operating Junction and Storage Temperature Range                  | $T_J, T_{stg}$   |                | - 55 to + 150    | °C   |      |
| Soldering Recommendations (Peak Temperature)                      | for 10 s         |                | 300 <sup>d</sup> |      |      |

#### Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$  V, starting  $T_J = 25$  °C,  $L = 40$  mH,  $R_g = 25$   $\Omega$ ,  $I_{AS} = 1.5$  A.
- $I_{SD} \leq 4.4$  A,  $dI/dt \leq 90$  A/ $\mu$ s,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150$  °C.
- 1.6 mm from case.

\* Pb containing terminations are not RoHS compliant, exemptions may apply

| THERMAL RESISTANCE RATINGS  |            |      |      |      |
|-----------------------------|------------|------|------|------|
| PARAMETER                   | SYMBOL     | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient | $R_{thJA}$ | -    | 120  | °C/W |

| SPECIFICATIONS ( $T_J = 25\text{ °C}$ , unless otherwise noted) |                     |  |   |      |      |           |               |
|---|---------------------|--|---|------|------|-----------|---------------|
| PARAMETER   | SYMBOL              | TEST CONDITIONS  |   | MIN. | TYP. | MAX.      | UNIT          |
| <b>Static</b>   |                     |  |   |      |      |           |               |
| Drain-Source Breakdown Voltage                                  | $V_{DS}$            | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$  |   | 500  | -    | -         | V             |
| $V_{DS}$ Temperature Coefficient                                | $\Delta V_{DS}/T_J$ | Reference to $25\text{ °C}$ , $I_D = 1\text{ mA}$  |   | -    | 0.59 | -         | V/°C          |
| Gate-Source Threshold Voltage                                   | $V_{GS(th)}$        | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$  |   | 2.0  | -    | 4.0       | V             |
| Gate-Source Leakage   | $I_{GSS}$           | $V_{GS} = \pm 20\text{ V}$   |   | -    | -    | $\pm 100$ | nA            |
| Zero Gate Voltage Drain Current                                 | $I_{DSS}$           | $V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$   |   | -    | -    | 25        | $\mu\text{A}$ |
|   |                     | $V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ °C}$  |   | -    | -    | 250       |               |
| Drain-Source On-State Resistance                                | $R_{DS(on)}$        | $V_{GS} = 10\text{ V}$   | $I_D = 0.22\text{ A}^b$                       | -    | -    | 3.0       | $\Omega$      |
| Forward Transconductance  | $g_{fs}$            | $V_{DS} = 50\text{ V}, I_D = 1.3\text{ A}^b$   |   | 1.5  | -    | -         | S             |
| <b>Dynamic</b>  |                     |  |   |      |      |           |               |
| Input Capacitance   | $C_{iss}$           | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$  |   | -    | 360  | -         | pF            |
| Output Capacitance  | $C_{oss}$           |  |   | -    | 92   | -         |               |
| Reverse Transfer Capacitance                                    | $C_{rss}$           |  |   | -    | 37   | -         |               |
| Total Gate Charge   | $Q_g$               | $V_{GS} = 10\text{ V}$   | $I_D = 2.1\text{ A}, V_{DS} = 400\text{ V}^b$ | -    | -    | 24        | nC            |
| Gate-Source Charge  | $Q_{gs}$            |  |   | -    | -    | 3.3       |               |
| Gate-Drain Charge   | $Q_{gd}$            |  |   | -    | -    | 13        |               |
| Turn-On Delay Time  | $t_{d(on)}$         | $V_{DD} = 250\text{ V}, I_D = 2.1\text{ A}, R_g = 18\text{ }\Omega, R_D = 120\text{ }\Omega^b$   |   | -    | 8.0  | -         | ns            |
| Rise Time   | $t_r$               |  |   | -    | 8.6  | -         |               |
| Turn-Off Delay Time   | $t_{d(off)}$        |  |   | -    | 33   | -         |               |
| Fall Time   | $t_f$               |  |   | -    | 16   | -         |               |
| Internal Drain Inductance                                       | $L_D$               | Between lead, 6 mm (0.25") from package and center of die contact  |   | -    | 4.0  | -         | nH            |
| Internal Source Inductance                                      | $L_S$               |  |   | -    | 6.0  | -         |               |
| <b>Drain-Source Body Diode Characteristics</b>                  |                     |  |   |      |      |           |               |
| Continuous Source-Drain Diode Current                           | $I_S$               | MOSFET symbol showing the integral reverse p - n junction diode    |   | -    | -    | 0.37      | A             |
| Pulsed Diode Forward Current <sup>a</sup>                       | $I_{SM}$            |  |   | -    | -    | 5.0       |               |
| Body Diode Voltage  | $V_{SD}$            | $T_J = 25\text{ °C}, I_S = 0.37\text{ A}, V_{GS} = 0\text{ V}^b$   |   | -    | -    | 1.6       | V             |
| Body Diode Reverse Recovery Time                                | $t_{rr}$            | $T_J = 25\text{ °C}, I_F = 2.1\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$   |   | -    | 260  | 520       | ns            |
| Body Diode Reverse Recovery Charge                              | $Q_{rr}$            |  |   | -    | 0.70 | 1.4       | $\mu\text{C}$ |
| Forward Turn-On Time  | $t_{on}$            | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )  |   |      |      |           |               |

**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

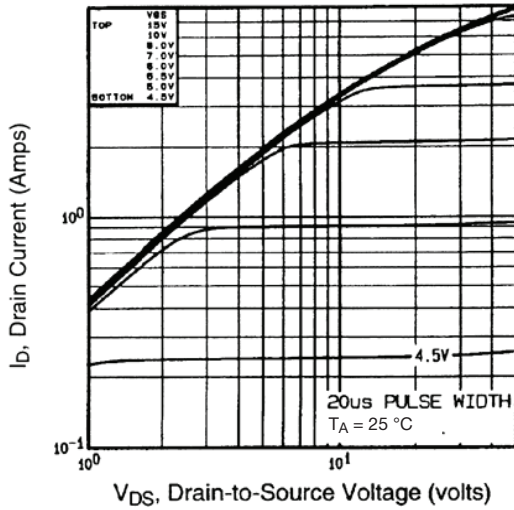


Fig. 1 - Typical Output Characteristics,  $T_A = 25\text{ }^\circ\text{C}$

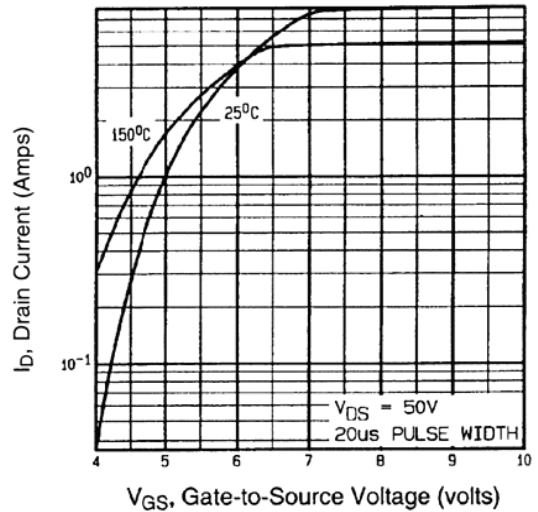


Fig. 3 - Typical Transfer Characteristics

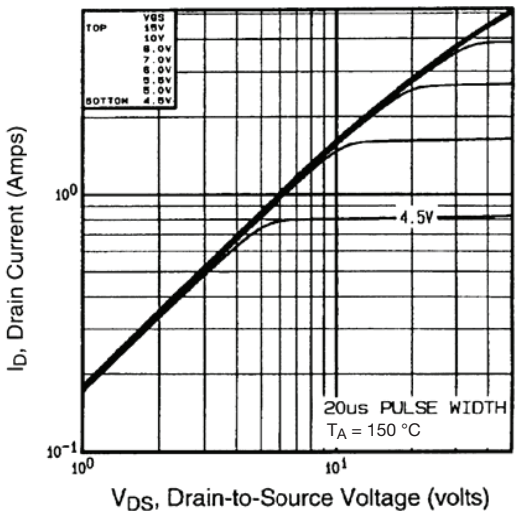


Fig. 2 - Typical Output Characteristics,  $T_A = 150\text{ }^\circ\text{C}$

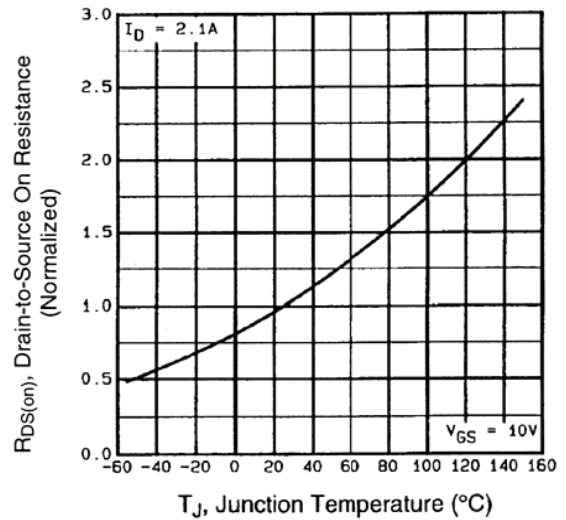


Fig. 4 - Normalized On-Resistance vs. Temperature

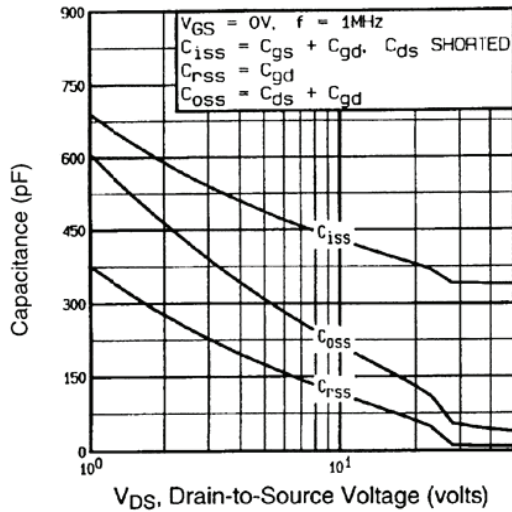


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

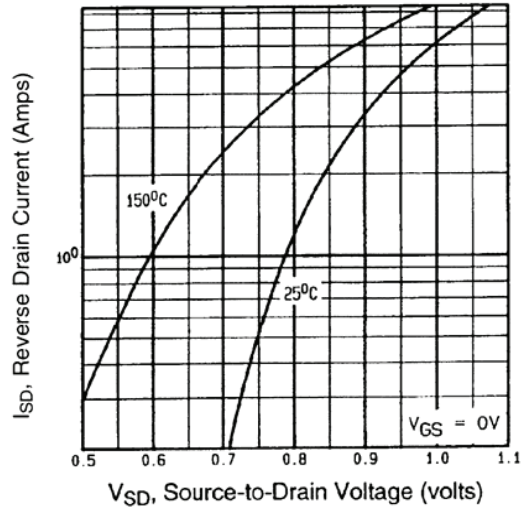


Fig. 7 - Typical Source-Drain Diode Forward Voltage

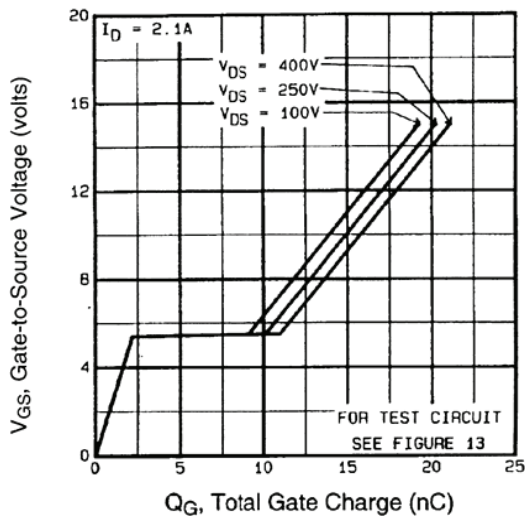


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

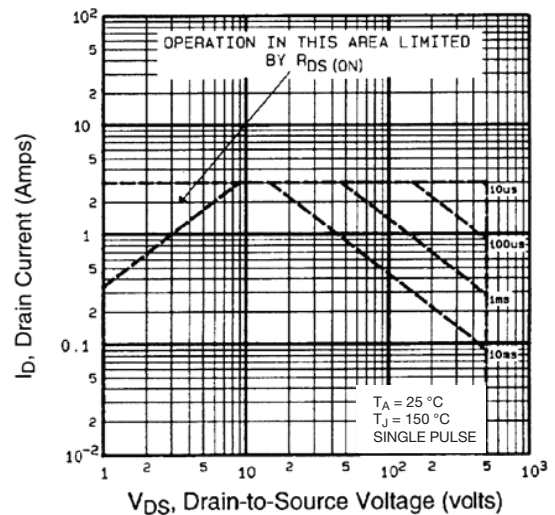


Fig. 8 - Maximum Safe Operating Area

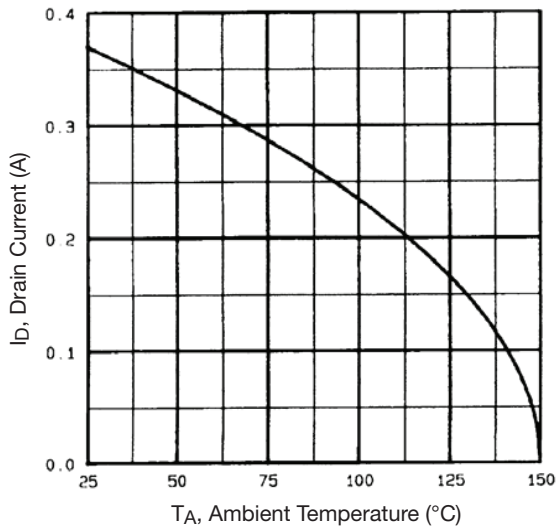


Fig. 9 - Maximum Drain Current vs. Ambient Temperature



Fig. 10a - Switching Time Test Circuit



Fig. 10b - Switching Time Waveforms

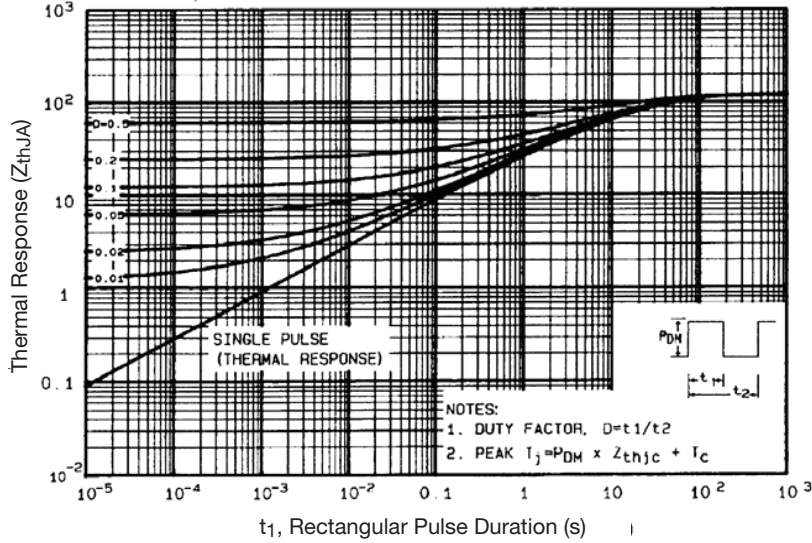


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

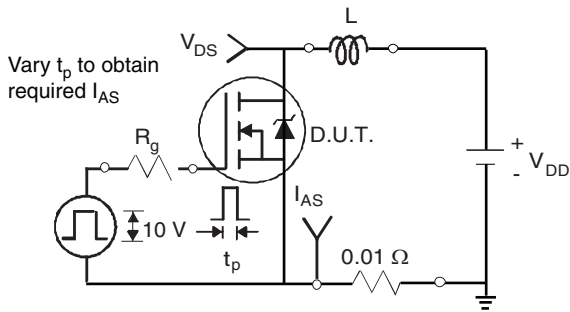


Fig. 12a - Unclamped Inductive Test Circuit



Fig. 12b - Unclamped Inductive Waveforms

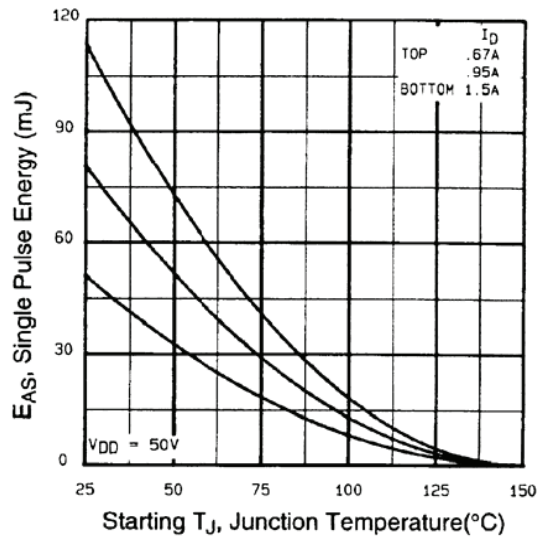


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

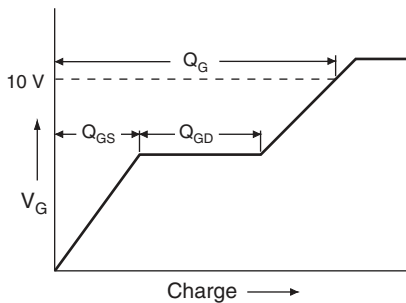


Fig. 13a - Basic Gate Charge Waveform

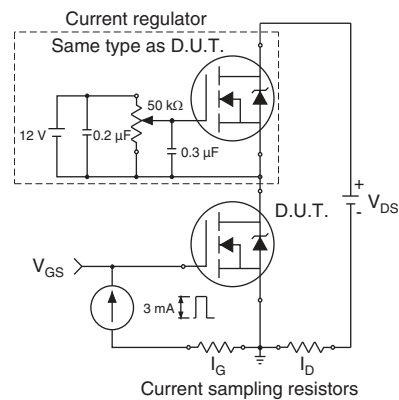


Fig. 13b - Gate Charge Test Circuit



**Note**

a.  $V_{GS} = 5\text{ V}$  for logic level devices

**Fig. 14 - For N-Channel**

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